SDB3005WT

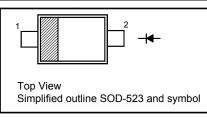
Surface Mount Schottky Barrier Diode

Features

- Ultra small power mold type
- Low forward voltage

PINNING

PIN	DESCRIPTION				
1	Cathode				
2	Anode				



Absolute Maximum Ratings (T_a = 25°C)

Parameter	Symbol	Value	Unit
Reverse Voltage	V_R	30	V
Forward Current	I _F	0.5	Α
Repetitive Peak Forward Current (tp ≤ 1 ms)	I _{FRM}	1	А
Peak Forward Surge Current (tp = 8.3 ms)	I _{FSM}	3	А
Power Dissipation	P _{tot}	310	mW
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _{stg}	- 55 to + 150	°C

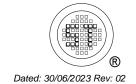
Thermal Characteristics

Parameter	Symbol	Value	Unit
Typical Thermal Resistance from Junction to Ambient 1)	$R_{\theta JA}$	400	°C/W

¹⁾Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Electrical Characteristics (T_a = 25°C)

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I _R = 500 µA	$V_{(BR)R}$	30	-	V
Forward Voltage at $I_F = 0.1$ mA at $I_F = 1$ mA at $I_F = 10$ mA at $I_F = 100$ mA at $I_F = 500$ mA	V _F	- - - -	180 200 270 360 500	mV
Reverse Current at $V_R = 10 \text{ V}$ at $V_R = 30 \text{ V}$	I _R	- -	200 500	μΑ
Total Capacitance at $V_R = 1 \text{ V}$, $f = 1 \text{ MHz}$	C_{d}	-	30	pF



SDB3005WT

Electrical Characteristic Curves

Fig 1. Forward Current Derating Curve

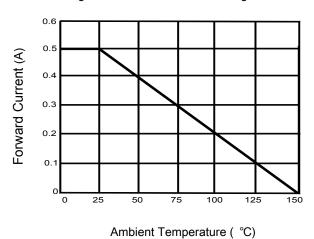
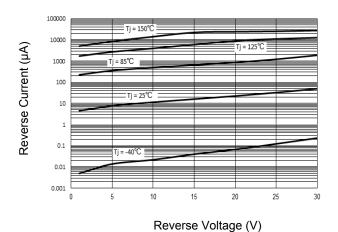
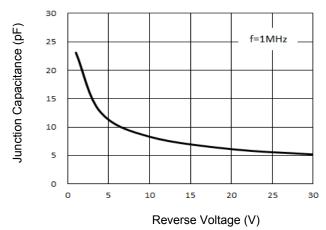


Fig 3. Reverse Characteristic Curve

Fig 2. Forward Characteristic Curve

Fig 4. Junction Capacitance

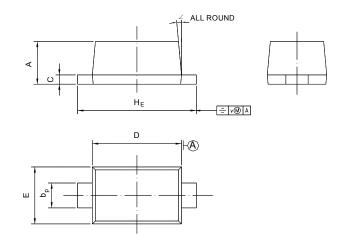




PACKAGE OUTLINE

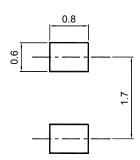
Plastic surface mounted package; 2 leads

SOD-523



UNIT	Α	bp	С	D	Е	H _E	V	_
mm	0.70 0.60		0.135 0.100	1.25 1.15	0.85 0.75	1.7 1.5	0.1	5°

Recommended Soldering Footprint



Packing information

Package	Tape Width	Pit	Pitch		Size	D. D. I.D. I.; O. I.;
	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity
SOD-523	8	4 ± 0.1	0.157 ± 0.004	178	7	4,000

Marking information

" LT " = Part No.

" III " = Cathode line

Font type: Arial



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